

# 10V Drive Nch MOSFET

## R6008FNJ

### ● Structure

Silicon N-channel MOSFET

### ● Features

- 1) Fast reverse recovery time ( $t_{rr}$ )
- 2) Low on-resistance.
- 3) Fast switching speed.
- 4) Gate-source voltage  
 $V_{GSS}$  guaranteed to be  $\pm 30V$ .
- 5) Drive circuits can be simple.
- 6) Parallel use is easy.

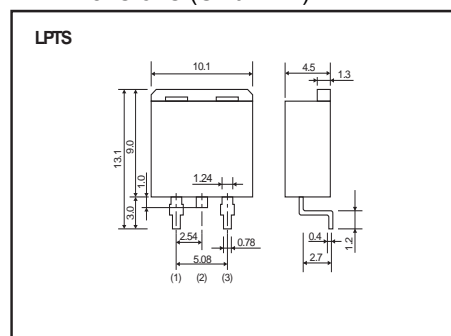
### ● Application

Switching

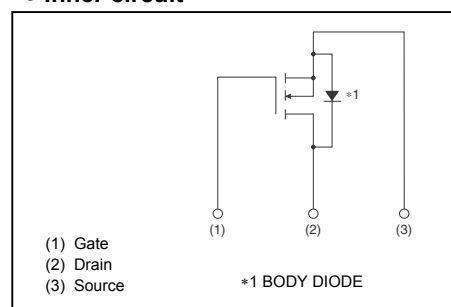
### ● Packaging specifications

Type	Package	Taping
	Code	TL
	Basic ordering unit (pieces)	1000
R6008FNJ		○

### ● Dimensions (Unit : mm)



### ● Inner circuit



### ● Absolute maximum ratings ( $T_a = 25^\circ C$ )

Parameter		Symbol	Limits	Unit
Drain-source voltage		$V_{DSS}$	600	V
Gate-source voltage		$V_{GSS}$	$\pm 30$	V
Drain current	Continuous	$I_D$ *3	$\pm 8$	A
	Pulsed	$I_{DP}$ *1	$\pm 32$	A
Source current (Body Diode)	Continuous	$I_S$ *3	8	A
	Pulsed	$I_{SP}$ *1	32	A
Avalanche Current		$I_{AS}$ *2	4	A
Avalanche Energy		$E_{AS}$ *2	4.3	mJ
Power dissipation ( $T_c=25^\circ C$ )		$P_D$	50	W
Channel temperature		$T_{ch}$	150	$^\circ C$
Range of storage temperature		$T_{stg}$	-55 to +150	$^\circ C$

\*1  $P_w \leq 10W$ , Duty cycle  $\leq 1\%$

\*2  $L = 500\mu H$ ,  $V_{DD} = 50V$ ,  $R_g = 25\Omega$ , starting  $T_{ch} = 25^\circ C$

\*3 Limited only by maximum temperature allowed.

### ● Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to Case	$R_{th(ch-c)}$	2.5	$^\circ C / W$

## ● Electrical characteristics (Ta = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Gate-source leakage	$I_{GSS}$	-	-	$\pm 100$	nA	$V_{GS}=\pm 30V, V_{DS}=0V$
Drain-source breakdown voltage	$V_{(BR)DSS}$	600	-	-	V	$I_D=1mA, V_{GS}=0V$
Zero gate voltage drain current	$I_{DSS}$	-	-	100	$\mu A$	$V_{DS}=600V, V_{GS}=0V$
Gate threshold voltage	$V_{GS(th)}$	2.0	-	4.0	V	$V_{DS}=10V, I_D=1mA$
Static drain-source on-state resistance	$R_{DS(on)}$ *	-	0.73	0.95	$\Omega$	$I_D=4A, V_{GS}=10V$
Forward transfer admittance	$ Y_{fs} $ *	2.5	5.0	-	S	$I_D=4A, V_{DS}=10V$
Input capacitance	$C_{iss}$	-	580	-	pF	$V_{DS}=25V$
Output capacitance	$C_{oss}$	-	450	-	pF	$V_{GS}=0V$
Reverse transfer capacitance	$C_{rss}$	-	25	-	pF	$f=1MHz$
Turn-on delay time	$t_{d(on)}$ *	-	20	-	ns	$I_D=4A, V_{DD}\approx 300V$
Rise time	$t_r$ *	-	25	-	ns	$V_{GS}=10V$
Turn-off delay time	$t_{d(off)}$ *	-	60	-	ns	$R_L=75\Omega$
Fall time	$t_f$ *	-	30	-	ns	$R_G=10\Omega$
Total gate charge	$Q_g$ *	-	20	-	nC	$I_D=8A,$
Gate-source charge	$Q_{gs}$ *	-	5	-	nC	$V_{DD}\approx 300V$
Gate-drain charge	$Q_{gd}$ *	-	10	-	nC	$V_{GS}=10V$

\*Pulsed

## ● Body diode characteristics (Source-Drain) (Ta = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward Voltage	$V_{SD}$ *	-	-	1.5	V	$I_s=8A, V_{GS}=0V$
Reverse Recovery Time	$t_{rr}$ *	-	67	-	ns	$I_s=8A, di/dt=100A/\mu s$

\*Pulsed

# ●Electrical characteristic curves

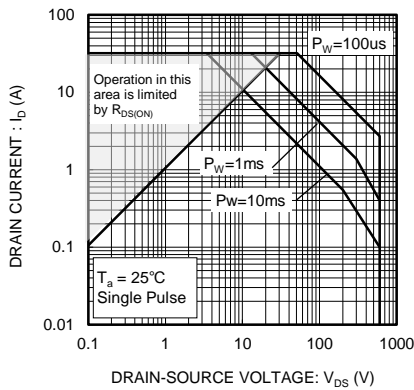


Fig.1 Maximum Safe Operating Area

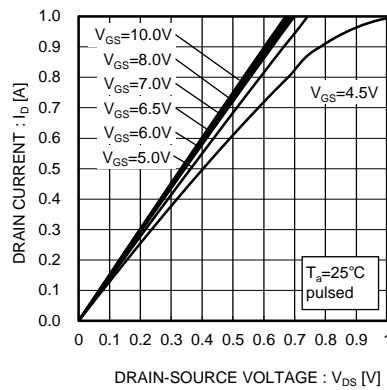


Fig.2 Typical Output Characteristics ( I )

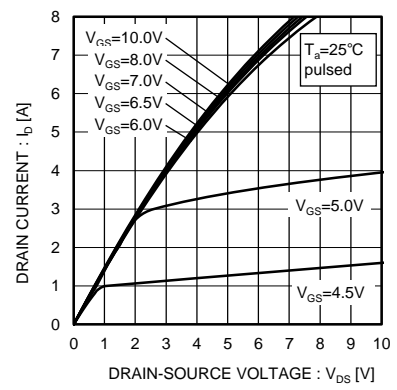


Fig.3 Typical Output Characteristics ( II )

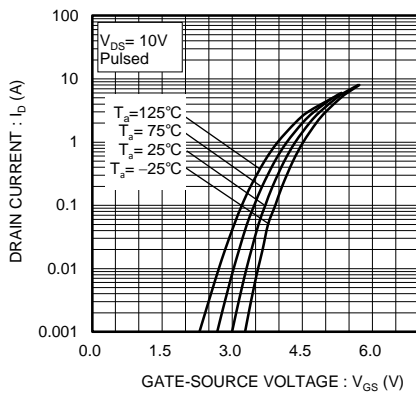


Fig.4 Typical Transfer Characteristics

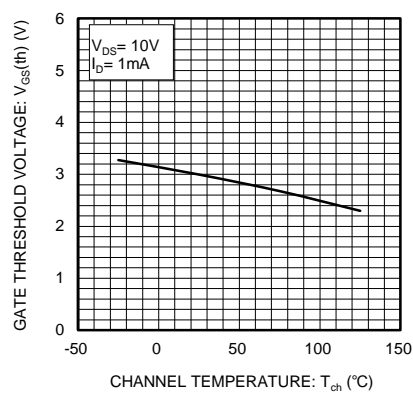


Fig.5 Gate Threshold Voltage vs. Channel Temperature

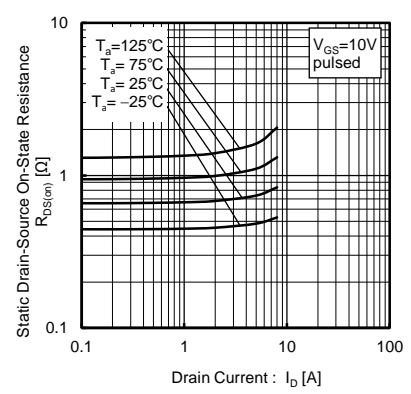


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current

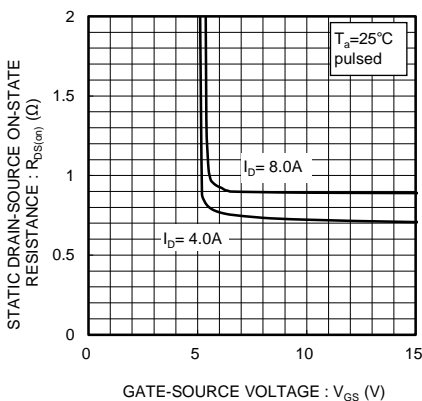


Fig.7 Static Drain-Source On-State Resistance vs. Gate Source Voltage

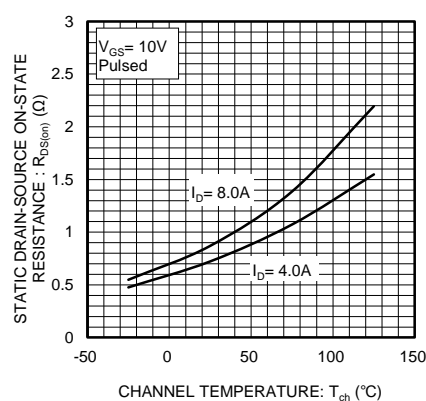


Fig.8 Static Drain-Source On-State Resistance vs. Channel Temperature

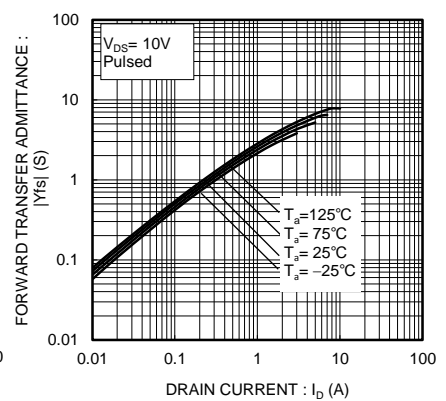


Fig.9 Forward Transfer Admittance vs. Drain Current

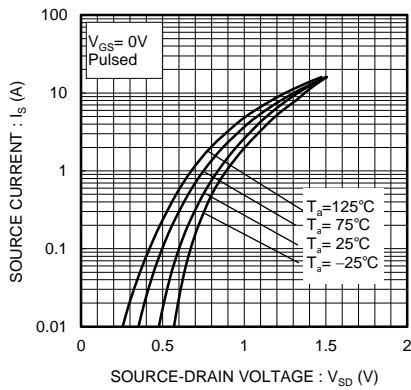


Fig.10 Source Current vs.  
Source-Drain Voltage

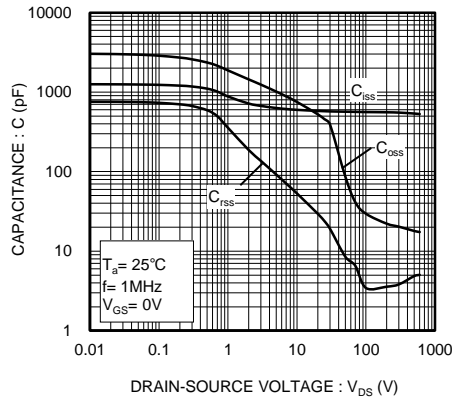


Fig.11 Typical Capacitance vs.  
Drain-Source Voltage

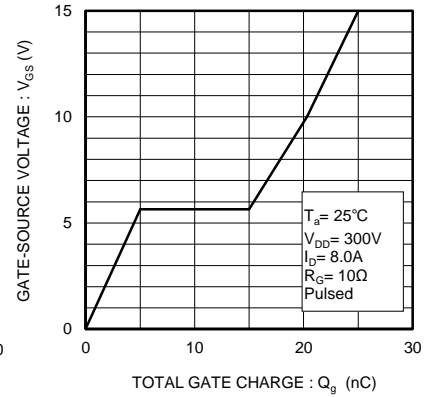


Fig.12 Dynamic Input Characteristics

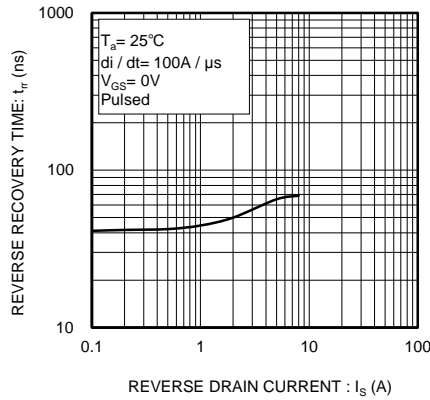


Fig.13 Reverse Recovery Time  
vs. Source Current

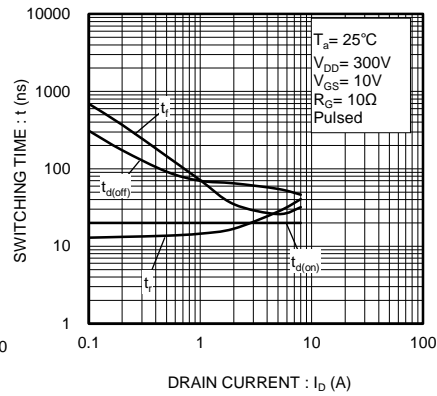


Fig.14 Switching Characteristics

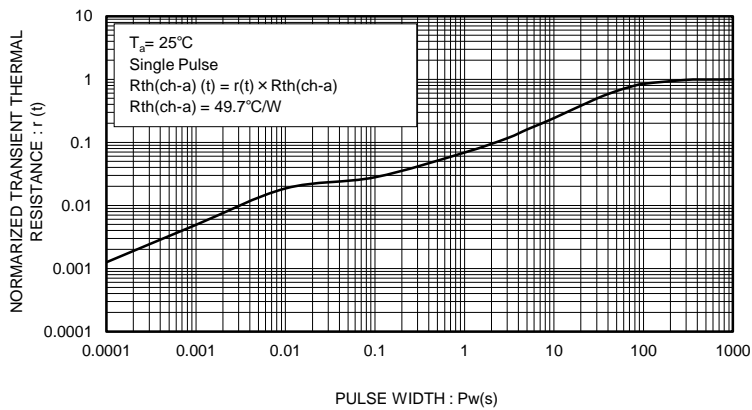


Fig.15 Normalized Transient Thermal Resistance vs. Pulse Width

## ● Measurement circuits

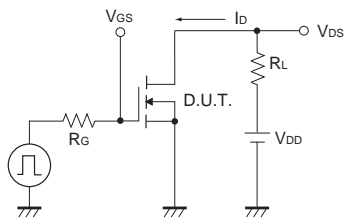


Fig.1-1 Switching Time Measurement Circuit

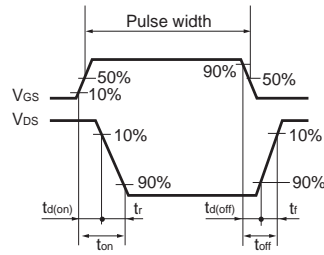


Fig.1-2 Switching Waveforms

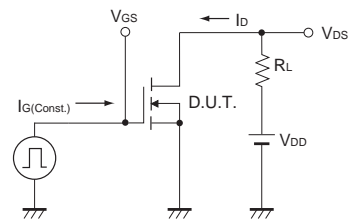


Fig.2-1 Gate Charge Measurement Circuit

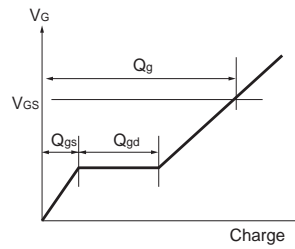


Fig.2-2 Gate Charge Waveform

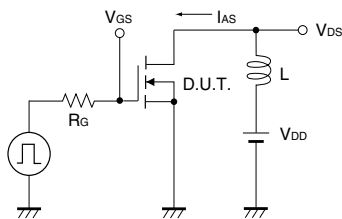


Fig.3-1 Avalanche Measurement Circuit

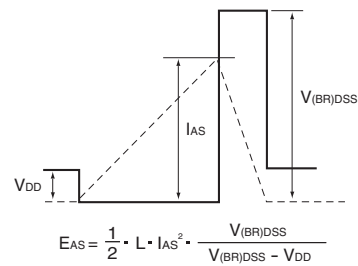


Fig.3-2 Avalanche Waveform

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